

Security advisory TN1436-ST-PSIRT: potential bypassing of Bluetooth® Low Energy Secure Connection authentication

Overview

This document describes the security advisory related to the potential bypassing of Bluetooth® Low Energy Secure Connections authentication. The affected products are listed in [Table 1](#).

Affected products

Table 1. Affected products

Part number	Embedded software
BlueNRG-1, BlueNRG-2	STSW-BLUENRG1-DK from version 2.1.0 to 3.2.2
BLUENRG-2N	STSW-BNRG2N-V320 and V330
BlueNRG-LP, BlueNRG-LPS	STSW-BNRGLP-DK from 1.0.0 to 1.2.0
STM32WB Series microcontrollers	STM32CubeWB version 1.14.1 and earlier

The evaluation boards using any of the foregoing products are also affected.

How to verify that the product is affected

In all the products listed above, the vulnerability is present only if Bluetooth® Low Energy Secure Connections (SC) is used for authentication, and the application has not initialized a random value for Out of band (OOB) pairing during the initialization of the Bluetooth® Low Energy stack.

Description of the potential vulnerability

An attacker device can coerce the affected product into successfully completing an OOB SC pairing, passing the two SC authentication stages, even without receiving any negotiated OOB data from the affected product itself. This results in the authentication of the attacker, thus providing unauthorized access to data requiring authentication.

Impact

When an attacker is within the Bluetooth® Low Energy range of an affected product, and the attacker has appropriate tools specially programmed to execute this attack, an unexpected access to the information protected by the Bluetooth® Low Energy Secure Connections authentication may occur.

Remediation/mitigation

After each initialization of the Bluetooth® Low Energy stack, call the `aci_gap_set_oob_data()` command to pass the random value to be used later during OOB pairing. The random value must be generated with 128 bits of entropy.

The steps are summarized in the following code example. The `hci_le_rand()` command is used to generate the random value. However any other source of entropy can be used instead, provided it conforms to the requirements of Bluetooth® Low Energy Core Specifications [Vol 2] Part H, Section 2.

```
uint8_t status, address[6] = {0,}, random[16];
status = hci_le_rand( random );
if ( status )
    system_error( );
status = hci_le_rand( random + 8 );
if ( status )
    system_error( );
status = aci_gap_set_oob_data( 0, 0, address, 1, 16, random );
if ( status )
    system_error( );
```

Credit

Purdue University and Pennsylvania State University.

Contact information

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Revision history

Table 2. Document revision history

Date	Revision	Changes
30-Nov-2022	1	Initial release.
13-Dec-2022	2	Changed document scope to public.

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